

REMARKS

Favorable reconsideration of this application in light of the following discussion is respectfully requested.

Claims 1-6 are presently active in this case. The present Amendment amends Claim 1 without introducing any new matter; and cancels withdrawn Claims 7-22 without prejudice or disclaimer.

The outstanding Office Action objected to the drawings and claims because of informalities. Claims 1-6 were rejected under 35 U.S.C. §112, second paragraph, as indefinite. Claims 1-6 were rejected under 35 U.S.C. §102(e) as anticipated by Tsukamoto et al. (U.S. Patent No. 6,703,565; herein “Tsukamoto”).

In response to the Restriction Requirement being made final, Claims 7-22, directed to non-elected inventions, are canceled. Applicants reserve the right to present claims directed to the non-elected inventions in a divisional application, which shall be subject to the third sentence of 35 U.S.C. §121.¹

In response to the objection to the drawings and the rejection of Claims 1-6 under 35 U.S.C. §112, second paragraph, Claim 1 is amended to recite “a sheet-like porous member having pores.” This feature finds non-limiting support in Applicants’ disclosure as originally filed, for example at page 9, lines 30-32, to recite “a porous sheet 1 being a sheet-like porous member, and a semiconductor chip 2 having electrodes 3 are prepared.” In addition, Claim 1 is amended to correct minor formalities and to better comply with U.S. claim drafting practice. In light of the amendments to independent Claim 1, Applicants believe that the rejection to Claims 1-6 under 35 U.S.C. §112, second paragraph, and to objection to drawings is overcome, as next discussed.

¹ “A patent issuing on an application with respect to which a requirement for restriction under this section has been made ... shall not be used as a reference ... against a divisional application.” See also MPEP 804.01.

To facilitate the understanding of the Applicants' invention, the present invention as disclosed in the Specification is next explained. As explained in Applicants' Specification from page 9, line 30, to page 10, line 19 with corresponding Figures 1A-1D, 2A-2D and 3, first, a porous sheet 1 is mounted to an electronic device 2 that includes electrodes 3.² The mounting of the porous sheet can be done by pressure sensitive adhesion. Subsequently, the porous sheet 1 is irradiated with an energy beam to carry out a pattern exposure to form latent images 5a for wirings and latent images 6a for vias.³ Then the latent images 5a and 6a are filled with a conductive material, for example by plating, to form wirings 5b and vias 6b.⁴

As further explained in a non-limiting embodiment in Applicants' Specification at page 8, lines 8-25, by applying a porous sheet 1, plating or etching liquid applied onto the porous sheet 1 can gather between the electronic device 2, and the porous sheet 1 can be easily washed away through the porous sheet, which would not be the case if the sheet 1 is not porous.

In view of amended independent Claim 1, it is believed that all pending claims are definite and no further rejection on that basis is anticipated. If, however, the Examiner disagrees, the Examiner is invited to telephone the undersigned who will be happy to work with the Examiner in a joint effort to derive mutually acceptable language.

In response to the rejection of Claims 1-6 under 35 U.S.C. §102(e), Applicants respectfully request reconsideration of this rejection and traverse the rejection, as discussed next.

Briefly recapitulating, Claim 1 relates to a method of connecting an electronic device, the method including, *inter alia*, the steps of: mounting an electrode of an electronic device closely on a sheet-like porous member having pores, the porous member having a

² See also for example Applicants' Figure 1A.

³ Idem Figure 1C and 3.

⁴ See Applicants' specification at page 10, lines 17-19.

photosensitive layer; selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams to form a latent image, the predetermined region including a portion close to the electrode; after the selectively irradiating, *filling pores* in the latent image *with a conductive material to form a conductive portion connected to the electrode*; and bonding the porous member, in which the conductive portion is formed by the filling, to the electronic device.

As explained in Applicants' specification from page 6, line 35, to page 7, line 22, Claim 1 improves upon background methods of connecting an electronic device, since the porous sheet 1 is connected to the electronic device 2 during the step of filling, the electric connection between the electrode 3 of the electronic device 2 will be improved.

Turning now to the applied reference, Tsukamoto describes a method of manufacturing a printed wiring board, wherein the wiring pattern 113 is first formed on a releasable supporting sheet 111,⁵ and in a next step, the wiring pattern 113 together with the releasable supporting sheet 111 is transferred onto an adhesive insulator sheet 114, so as to connect the wiring pattern 113 with the conductive portions 116 the portions 116 forming interlayer connections.⁶ However, Tsukamoto fails to teach or suggest filling pores in the latent image with a conductive material to form a conductive portion *connected to the electrode*. As explained above, Tsukamoto first forms wirings 113 on the supported sheet 111, and then connects the sheet to the insulator sheet 114 with the conductive portions 116.

Therefore, the applied reference fails to teach or suggest every feature recited in Applicants' claims, so that Claims 1-6 are believed to be patentably distinct over Tsukamoto. Accordingly, Applicants respectfully traverse, and request reconsideration of, the rejection based on Tsukamoto.⁷

⁵ See Tsukamoto at column 4, lines 64-67 and in corresponding Figure 1B.

⁶ See Tsukamoto at column 5, lines 18-35 and in corresponding Figure 1D.

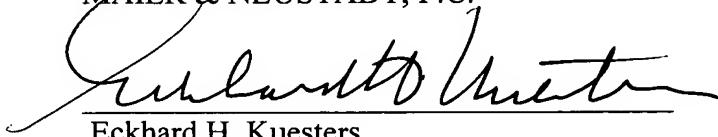
⁷ See MPEP 2131: "A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference," (Citations omitted) (emphasis added).

Consequently, in view of the present Amendment, no further issues are believed to be outstanding in the present application, and the present application is believed to be in condition for formal Allowance. A Notice of Allowance for Claims 1-6 is earnestly solicited.

Should the Examiner deem that any further action is necessary to place this application in even better form for allowance, the Examiner is encouraged to contact Applicants' undersigned representative at the below listed telephone number.

Respectfully submitted,

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See also MPEP 2143.03: "All words in a claim must be considered in judging the patentability of that claim against the prior art."